Проконсультироваться и купить данное оборудование вы можете в компании «АНД-Системс» адрес: 125480, г.Москва, ул.Туристская, д.33/1; site: <u>https://andpro.ru</u> тел: +7 (495) 545-4870 email: info@andpro.ru При обращении используйте промокод AND-PDF и получите скидку.

QuickSpecs

HP ProBook 630 G8 Notebook PC

Overview

UEFI HP ProBook 630 G8 Notebook PC



1. Internal Microphones (2)

- 2. Webcam LED (Optional)
- 3. HD Camera (Optional)
- 4. IR Camera LEDs (Optional)
- 5. Clickpad

Left

- 6. Smartcard Reader (Optional)
- 7. Audio Combo Jack
- 8. USB 3.1 Gen 1 Port
- 9. Nano Security Lock Slot (Lock sold separately)



Overview



Right

- 1. Power Button Key
- 2. Power Connector
- 3. USB 3.1 Gen 2 Type-C[®]
- 4. USB 3.1 Gen 1 Port

- 5. HDMI Port (Cable not included)
- 6. Touch Fingerprint Sensor (select models)



Overview

At a Glance

- New mechanical design Smaller footprint and Light weight
- Powerful quad core 11th Gen Intel[®] Core[™] U-Series
- HP Sure View Gen3 panel
- Physical HP Privacy Camera (Optional)
- HP Fast Charge Charge up to 50% in 30 minutes
- Wi-Fi 6 capability (Optional)
- Multi Factor Authentication IR camera and hardened fingerprint sensor (Optional)
- Rich IO ports with charging USB
- Responsiveness w/Modern Standby and Wake on Fingerprint Sensor (Optional)
- Backlit keyboard option and new programmable key
- Nice range of display option from HD, FHD, all the way to SureView option
- Passed 19 MIL STD 810H tests¹
- 1. MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP ProBook 630 G8 Notebook PC

OPERATING SYSTEMS

Preinstalled	Windows 10 Pro 64 – HP recommends Windows 10 Pro ¹ Windows 10 Pro 64 (National Academic only) ² Windows 10 Home 64 ¹
	Windows 10 Home Single Language 64 ¹ Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) ¹ FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

Supported Version

HP tested Windows 10, version 1809 on this platform For testing information on newer versions of Windows10, please see: https://support.hp.com/document/c05195282.

PROCESSORS

Intel[®] Core[™] i7-1165G7 processor (Up to 4.7 GHz with Intel[®] Turbo Boost Technology, 12 MB L3 cache, 4 cores)^{3,4 5,6} Intel[®] Core[™] i5-1135G7 processor (Up to 4.2 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4 5,6} Intel[®] Core[™] i3-1115G4 processor with Intel[®] UHD Graphics (Up to 4.1 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 2 cores)^{3,4 5,6}

Processors Family

11th Generation Intel[®] Core[™] i7 processor (i7-1165G7)⁶ 11th Generation Intel[®] Core[™] i5 processor (i5-1135G7)⁶ 11th Generation Intel[®] Core[™] i3 processor (i3-1115G4)⁶

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET



Chipset is integrated with processor

GRAPHICS

Integrated

Intel[®] Iris[®] X^e Graphics (Core i5 and Core i7)⁴¹ Intel[®] UHD Graphics (Core i3)⁷

Supports

Support HD decode, DX12, HDMI 1.4b

7. HD content required to view HD images.

41.Intel[®] Iris[®] Xe Graphics capabilities require system to be configured with Intel[®] Core[™] i5 or i7 processors and dual channel memory. Intel[®] Iris[®] Xe Graphics with Intel[®] Core[™] i5 or 7 processors and single channel memory will only function as UHD graphics.

DISPLAYS

Internal

Non-Touch

33.8 cm (13.3") diagonal HD SVA eDP anti-glare narrow bezel ultraslim, 250 nits, 45% NTSC (1366 x 768)^{7,9}

33.8 cm (13.3") diagonal HD SVA eDP anti-glare narrow bezel flat, 250 nits, 45% NTSC for HD camera (1366 x 768) ^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare narrow bezel slim, 250 nits, 45% NTSC (1920 x 1080) ^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare narrow bezel flat, 250 nits, 45% NTSC for HD camera (1920 x 1080) ^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare narrow bezel flat, 250 nits, 45% NTSC for HD+IR camera (1920 x 1080))^{7,9} 33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare Low Power narrow bezel flat, 400 nits, 72% NTSC for HD camera (1920 x 1080))^{7,9}

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare Low Power narrow bezel flat, 400 nits, 72% NTSC for HD+IR camera (1920 x 1080)) ^{7,8,9}

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare narrow bezel flat with HP Sure View Gen3 Integrated Privacy Screen, 1000 nits, 72% NTSC for HD+IR camera (1920 x 1080)^{7,8,9,10,*}

Touch

33.8 cm (13.3") diagonal FHD SVA eDP narrow bezel ultraslim touch-on-panel screen, 250 nits, 45% NTSC for HD camera (1920x1080) ^{7,8,9,*}

HDMI

Supports resolutions up to 4K 30Hz

7. HD content required to view HD images.

8. Sold separately or as an optional feature.

9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

10. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

* Actual brightness will be lower with HP Sure View or touch screen.



Docking station model	Total number of supported displays (incl. the notebook) display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock G2	3	Dual 4K @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	System only runs at alt- mode speed
HP Elite USB-C Dock G5	3	Three 1680x1050 @ 60 Hz Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock G2	3	Dual 4K @ 60Hz Single 5K @ 60Hz	1xHDMI, 2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary M.2 Storage

128 GB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹¹ 256 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive¹¹ 256 GB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹¹ 256 GB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹¹ 512 GB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹¹ 512 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive¹¹ 512 GB PCIe[®] Gen3x4 NVMe[™] M.2 SED SSD TLC¹¹ 512 GB Intel[®] PCIe[®] NVMe[™] QLC M.2 SSD with 32 GB Intel[®] Optane[™] memory H10 ^{11,*} 1 TB PCIe[®] NVMe[™] M.2 TLC Solid State Drive¹¹

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

*Intel[®] Optane[™] H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel[®] Core[™] processor, BIOS version with Intel[®] Optane[™] supported, Windows 10 64-bit, and an Intel[®] Rapid Storage Technology (Intel[®] RST) driver.

MEMORY

Maximum Memory

64 GB DDR4-3200 SDRAM 12

Memory

64 GB DDR4-3200 SDRAM (2 x 32 GB)¹² 32 GB DDR4-3200 SDRAM (1 x 32 GB)¹² 32 GB DDR4-3200 SDRAM (2 x 16 GB)¹² 16 GB DDR4-3200 SDRAM (1 x 16 GB)¹² 16 GB DDR4-3200 SDRAM (2 x 8 GB)¹² 12 GB DDR4-3200 SDRAM (4 GB and 8 GB (1 x 8 GB)¹² 8 GB DDR4-3200 SDRAM (1 x 8 GB)¹² 8 GB DDR4-3200 SDRAM (2 x 4 GB)¹² 4 GB DDR4-3200 SDRAM (1 x 4 GB)¹²

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable DDR4 PC4 SODIMMS, (Tiger Lake runs at 3200) Supports Dual Channel Memory

12. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



NETWORKING/COMMUNICATIONS

WLAN

Intel[®] Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth[®] 5 Combo, non-vPro^{®TM 13} Intel[®] Dual Band Wi-Fi 6 AX201 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth[®] 5 Combo, non-vPro^{®TM 13}

NFC

NFC Mirage WNC XRAV-1

Ethernet

Intel 10/100/1000 NIC 14

13. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

14. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers (70dB) Integrated microphone (Dual Array)

Camera

720p HD Camera⁷ 720p HD Camera+IR Camera ^{7,8}

7. HD content required to view HD images.
 8. Sold separately or as an optional feature.



Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with optional backlit function

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

F1 - Display Switching F2 - Blank or SureView On/Off F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - Insert F11 - Airplane mode F12 - Programmable key

Hiden Function Keys

Fn+R – Break Fn+S – Sys Rq Fn+C – Scroll Lock

SOFTWARE AND SECURITY

Preinstalled Software

HP BIOSphere Gen5¹⁵ HP Drive Lock & Automatic Drive Lock BIOS Update via Network Master Boot Record Security Power On Authentication HP Secure Erase¹⁷ Absolute Persistence Module¹⁸ HP LAN-Wireless Protection Pre-boot Authentication

Software

HP Connection Optimizer ¹⁶ HP Image Assistant HP Hotkey Support myHP HP Support Assistant ¹⁹ HP Noise Cancellation Software HSA Fusion for Commercial HSA Telemetry for Commercial HSA Telemetry for Commercial HP Notifications HP Privacy Settings HP Wireless Button Driver HP Power Manager Buy Office (sold separately)



Manageability Features

HP Driver Packs (download) ²⁰ HP Manageability Integration Kit Gen3 (download) ²¹ HP System Software Manager (SSM) (download) HP BIOS Config Utility (BCU) (download) HP Client Catalog (download) HP Client Management Script Library (download)

Client Security Software

HP Client Security Manager Gen6²² Windows Defender²³

Security Management

Pre-boot Authentication USB enable/disable (via BIOS) Power-on password (via BIOS) Setup password (via BIOS) HP Fingerprint Sensor ²⁴ Support for chassis padlocks and cable lock devices HP Pro Security Edition*.** HP Sure Click ²⁵ HP Sure Sense ²⁶ HP Sure Start Gen6 ²⁷ HP Sure Admin ²⁸ HP Sure Recover Gen3 ²⁹ HP Sure Run Gen3 ³⁰ TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)(FIPS 140-2 Level 2 Certified) ³¹

Security

ТРМ

Model: Infineon SLB9670 Version: 7.85 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes

Smartcard Reader

Model number: Alcor AU9560 FIPS 201 Compliant: Yes IPv6 Compliance Yes

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) Yes UEFI version: 2.7

15. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

16. HP Connection Optimizer requires Windows 10.

17. HP Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

18. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/. 19. HP Support Assistant requires Windows and Internet access.



Technical Specifications

20. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement. 21. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement. 22. HP Client Security Manager Gen6 requires Windows and is available on the select HP PCs. 23. Windows Defender Opt in and internet connection required for updates. 24. HP Fingerprint sensor is an optional feature that must be configured at purchase. 25. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A SureClick for complete details. 26. HP Sure Sense requires Windows 10. 27 HP Sure Start Gen6 is available on select HP PCs. 28. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store. 29. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. 30. HP Sure Run Gen3 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel[®] or AMD processors. 31. Firmware TPM is version 2.0. *HP Pro Security Edition is available preloaded on select HP PCs and includes HP Sure Click Pro and HP Sure Sense Pro. 3-year license required. The HP Pro Security Edition software is licensed under the license terms of the HP End User License Agreement (EULA) that can be found at:https://h30670.www3.hp.com/ecommerce/common/disclaimer.do#EN_US as modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for thirty-six (36) months thereafter ("Initial Term"). At the end of the Initial Term you may either (a)

purchase a renewal license for the HP Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.

**HP Pro Security Edition is optimized for the SMB environment and ships pre-configured - manageability is optional. The HP Pro Security Edition supports a limited tool set that can be used by the HP Manageability Integration Kit which can be downloaded from http://www.hp.com/go/clientmanagement



Technical Specifications

POWER

Power Supply

HP Smart 65 W External AC power adapter ³² HP Smart 65 W EM External AC power adapter ³² HP Smart 65 W USB Type-C[®] adapter ³² HP Smart 45 W External AC power adapter ³² HP Smart 45 W USB Type-C[®] adapter ³²

Primary Battery HP Long Life 3-cell, 45 Wh Polymer ³³

Power Cord 3-wire plug - 1m ³²

2-wire plug - 1m³²

Battery life MM18: Up to 12 hours and 45 minutes

Battery Weight 190 g

32. Availability may vary by country.
 33. Battery is internal and not replaceable by customer. Serviceable by warranty.

WEIGHTS & DIMENSIONS

Product Weight ³⁴ Starting at 2.81 lb Starting at 1.28 kg (400 nits display only)

Product Dimensions (w x d x h) Metal bottom cover:

12.08 x 8.2 x 0.62 in 30.69 x 20.84 x 1.59 cm

Plastic bottom cover: 12.08 x 8.2 x 0.69 in 30.69 x 20.84 x 1.77 cm

34. Weight will vary by configuration.



PORTS/SLOTS

Ports

USB 3.1 Gen 2 Type-C[®] (Power delivery, DisplayPort[™] 1.4)
 USB 3.1 Gen 1, (1 Powered port, 1 Power delivery)
 HDMI 1.4b ³⁵
 Headphone/microphone combo jack
 AC power

Expansion Slots 1 Smart Card Reader (optional)

35. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year and 3-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.³⁶

36. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance	ENERGY STAR [®] certified
Energy Efficiency Compliance	EPEAT [®] 2019 Silver ³⁷
Environmental Specifications	Low halogen ³⁸
Environmental Specifications	TCO NB 8.0 Certification

37. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit http://www.epeat.net for more information.

38. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.



SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	
Nominal Operating Voltage	19 V
Average Operating Power	4.62 W
Integrated graphics	Yes
Discrete Graphics	N/A
Max Operating Power	UMA < 45W
Temperature	
Operating	32° to 95° F (0° to 35° C)
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	0.75 arms
Operating	0.75 grms
Non-operating	1.50 grms
Altitude (unpressurized)	$(0, t_0, 10, 0, 0, 0, t_0, 10, 2, 4, t_0, 2, 0, 4, 0, m)$
Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating Planned Industry Standard Certifications	-50 to 40,000 ft (-15.24 to 12,192 m)
UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR®	Select models ³⁹
EPEAT®	EPEAT [®] 2019 Gold in U.S. ⁴⁰
Australia /	Yes
NZ A – Tick Compliance CCC	Yes Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marketing Compliance	Yes
BNCI or BELUS	Yes
CIT	
	Yes
GOST	Yes
Saudi Arabian Compliance (ICCP) SABS	Yes Yes
COUC	103

39. Configurations of the HP ProBook 630 G8 that are ENERGY STAR[®] certified are identified as HP ProBook 630 G8 ENERGY STAR on HP websites and on http://www.energystar.gov.

40. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit www.epeat.net for more information.



DISPLAYS

NOTE: All specifications represent the typical specifications provided by hp's component manufacturers; actual performance may vary either higher or lower.

*Actual brightness will be lower with HP Sure View or touch screen.

Panel LCD 13.3 inch FHD (1920x1080) Anti-Glare	Outline Dimensions (W x H x D) Active Area	300.56 x 187.77 mm (max) (w/ PCB & w/o bracket)
WLED UWVA 45% NTSC		293.76 x 165.24 mm (typ.)
250nits eDP 1.2 w/o PSR	Weight Diagonal Size	260 g (max.) 13.3 (inch)
slim NWBZ	Thickness	3.0 (mm) max
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	Anti-glare
	Touch Enabled	
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85
Panel LCD 13.3 inch FHD	Outline Dimensions (W x H x D)	300.56 x 177.77 mm (max)
(1920x1080) Anti-Glare	Active Area	293.76 x 165.24 mm (typ.)
WLED UWVA 45% NTSC 250	Weight	260 g (max.)
nits eDP slim Touch on Panel NWBZ)	Diagonal Size	13.3 inch
ranel NWDZ)	Thickness	3.0 mm/ 5.0 mm (PCB) (max)
	Interface	eDP1.2
	Surface Treatment	Anti-glare On - cell
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60Hz
	Brightness	250 nits*
	Dirgintiless	250 1113
	Divel Pecolution	1920 v1080 (EHD)
	Pixel Resolution	1920 x1080 (FHD) BGB Stripe
	Format	RGB Stripe
	Format Backlight	RGB Stripe LED
	Format Backlight Color Gamut Coverage	RGB Stripe LED 45% of NTSC
	Format Backlight Color Gamut Coverage Color Depth	RGB Stripe LED 45% of NTSC 6 bits (Hi FRC supportive w/ condition to enable)
	Format Backlight Color Gamut Coverage	RGB Stripe LED 45% of NTSC



Technical Specifications

Panel LCD 13.3 inch FHD	Outline Dimensions (W x H x D)	299.06 x 186.54 mm (max)
(1920x1080) Anti-Glare	Active Area	293.76 x 165.24 mm (typ.)
WLED UWVA 72% NTSC 1000 nits eDP 1.4+PSR2	Weight	255 g (max)
flat Privacy NWBZ Gen3	Diagonal Size	13.3 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.4 + PSR (4 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	2000:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	1000 nits*
	Pixel Resolution	1920 x 1080 (FHD)
	Format	RGB
	Backlight	LED
	Color Gamut Coverage	100% of sRGB
	Color Depth	8 bits
	Viewing Angle	UWVA 85/85/85

Panel LCD 13.3 inch FHD (1920x1080) Anti-Glare WLED UWVA 72% NTSC 400 nits eDP 1.4+PSR2 ultraslim LP NWBZ

Outline Dimensions (W x H x D)	299.06 x 185.54 mm (max)
Active Area	293.76 x 165.24 mm (typ.)
Weight	170 g (max)
Diagonal Size	13 inch
Thickness	2.0 mm (max)
Interface	eDP 1.4 + PSR2 (2 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1200:1 (typ.)
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	72% of NTSC
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85



Technical Specifications

Panel LCD 13.3 inch HD (1366x768) Anti-Glare WLED SVA 45% NTSC 250 nits eDP NWBZ ultraslim

Outline Dimensions (W x H x D)	300.56 x 187.77 max. (w/ PCB & w/o bracket)
Active Area	293.83 x 165.20 typ
Weight	260 max.
Diagonal Size	13.3"
Thickness	3.0mm max.
Interface	eDP 1.2 (1 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	300:1 (typ)
Refresh Rate	60 Hz
Brightness	250 nits
Pixel Resolution	1366 x 768 (HD)
Format	RGB
Backlight	LED
Color Gamut Coverage	45% of NTSC
Color Depth	6 bits
Viewing Angle	SVA 45/45/15/35



* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

STORAGE AND DRIVES*

SSD 128GB 2280 PCle-3x2 Three Layer CellForm FactorM.2 2280 Capacity128 GB NAND TypeTLC Height0.087 in (22 mm) Weight0.087 in (22 mm) WeightWeight0.02 lb (10 g) InterfaceMaximum Sequential Read1400 ~ 2100 MB/s Logical BlocksVMMe Three Layer CellForm FactorSSD 118 2280 PCle-3x4 NVMe Three Layer CellForm FactorMight0.22 lb (10 g) InterfaceVMMe Three Layer Cell single-sidedForm FactorMuthM.2 2280 CapacityCapacity1 TB NAND TypeNUMe Three Layer Cell single-sidedForm FactorMaximum Sequential Read Maximum Sequential Write0.09 in (2.3 mm) MidthMidth0.87 in (22 mm) WeightMidth0.87 in (22 mm) WeightMidth0.98 in (2.2 mm) WeightMidth0.98 in (22 mm) WeightMidth0.98 in (22 mm) WeightMidth0.92 in (10 g) InterfaceMaximum Sequential Read Maximum Sequential Read3100 ~ 3500 MB/s Maximum Sequential Write 2770 - 3037 MB/s Logical BlocksLogical Blocks2,000,409,264 Operating TemperatureSet 158*F (0* to 70°C) [ambient temp] FeaturesFeatures32* to 158*F (0* to 70°C) [ambient temp] Features			
NAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMeMaximum Sequential Read1400 ~ 2100 MB/sMaximum Sequential Write800 ~ 1200 MB/sLogical Blocks250,069,680Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCIe-3x4Form FactorM.2 2280NVMe Three Layer CellCapacity1 TBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Form Factor	M.2 2280
Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMeMaximum Sequential Read1400 ~ 2100 MB/sLogical Blocks250,069,680Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCIe-3x4Form FactorNVMe Three Layer CellCapacityInterfaceNAND TypeHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Wight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write2770 ~ 3037 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]	Three Layer Cell	Capacity	128 GB
Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMeMaximum Sequential Read1400 ~ 2100 MB/sMaximum Sequential Write800 ~ 1200 MB/sLogical Blocks250,069,680Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCIe-3x4Form FactorNVMe Three Layer CellForm FactorInterface0.9 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write2770 ~ 3037 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		NAND Type	TLC
Weight0.02 lb (10 g)InterfacePCle NVMeMaximum Sequential Read1400 ~ 2100 MB/sMaximum Sequential Write800 ~ 1200 MB/sLogical Blocks250,069,680Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCle-3x4Form FactorM.2 2280Capacity1 TBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write2770 ~ 3037 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Height	0.09 in (2.3 mm)
InterfacePCle NVMeMaximum Sequential Read1400 ~ 2100 MB/sMaximum Sequential Write800 ~ 1200 MB/sLogical Blocks250,069,680Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCle-3x4Form FactorM.2 2280NVMe Three Layer Cell single-sidedForm FactorM.2 2280VMMe Three Layer Cell single-sidedForm FactorM.2 2280VMMe Three Layer Cell single-sidedForm FactorM.2 2280NAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential ReadMaximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential WriteLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]S2° to 158°F (0° to 70°C) [ambient temp]		Width	0.87 in (22 mm)
Maximum Sequential Read1400 ~ 2100 MB/sMaximum Sequential Write800 ~ 1200 MB/sLogical Blocks250,069,680Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCIe-3x4Form FactorM.2 2280NVMe Three Layer Cell single-sidedForm FactorM.2 2280WMe Three Layer Cell single-sidedForm FactorM.2 2280Width0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write2770 ~ 3037 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Weight	0.02 lb (10 g)
Maximum Sequential Write Logical Blocks800 ~ 1200 MB/sLogical Blocks250,069,680Operating Temperature Features32° to 158°F (0° to 70°C) [ambient temp]SSD 1TB 2280 PCle-3x4 NVMe Three Layer Cell single-sidedForm FactorM.2 2280Capacity1 TBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write Logical Blocks2770 ~ 3037 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Interface	PCIe NVMe
Logical Blocks250,069,680Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCle-3x4 NVMe Three Layer Cell single-sidedForm FactorMAND Type1 TBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write2770 ~ 3037 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Read	1400 ~ 2100 MB/s
Operating Temperature Features32° to 158°F (0° to 70°C) [ambient temp] FeaturesSSD 1TB 2280 PCle-3x4 NVMe Three Layer Cell single-sidedForm Factor Capacity NAND TypeM.2 2280 TLC HeightMAND Type HeightTLC NAND TypeM.2 22 mm) VidthWidth Weight0.09 in (2.3 mm) 0.02 lb (10 g) Interface0.02 lb (10 g) InterfaceInterface Maximum Sequential Read Logical Blocks Operating Temperature3100 ~ 3500 MB/s 2.000,409,264 0.0°C) [ambient temp]		Maximum Sequential Write	800 ~ 1200 MB/s
FeaturesATA Security; DIPM; TRIM; DEVSLPSSD 1TB 2280 PCle-3x4 NVMe Three Layer Cell single-sidedForm FactorM.2 2280 CapacityCapacity1 TB NAND TypeTLC HeightHeight0.09 in (2.3 mm) Width0.87 in (22 mm) 0.02 lb (10 g) InterfaceWeight0.02 lb (10 g) InterfaceMaximum Sequential Read3100 ~ 3500 MB/s 3100 ~ 3500 MB/s Logical BlocksQperating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Logical Blocks	250,069,680
SSD 1TB 2280 PCle-3x4 NVMe Three Layer Cell single-sidedForm FactorM.2 2280 CapacityNAND Type1 TBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
NVMe Three Layer Cell single-sidedCapacity1 TBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write2770 ~ 3037 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Features	ATA Security; DIPM; TRIM; DEVSLP
Features ATA Security; TRIM; L1.2	NVMe Three Layer Cell	Capacity NAND Type Height Width Weight Interface Maximum Sequential Read Maximum Sequential Write Logical Blocks	1 TB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCle NVMe Gen3X4 3100 ~ 3500 MB/s 2770 ~ 3037 MB/s 2,000,409,264
			-



SSD 256GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	256 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	2100 ~ 2200 MB/s
	Maximum Sequential Write	900 ~ 1400 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (optional); TRIM; L1.2
	reatures	
SSD 512GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	512 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	2200 ~ 2300 MB/s
	Maximum Sequential Write	1000 ~ 1600 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (optional); TRIM; L1.2
	Faura Factori	N 2 2200
SSD 512GB 2280 PCIe- 3x2x2 NVMe+SSD 32GB 3D	Form Factor	M.2 2280 512 GB
Xpoint	Capacity	
	NAND Type	QLC+3D XPoint 0.09 in (2.3 mm)
	Height Width	0.87 in (22 mm)
	Weight Interface	0.02 lb (10 g) PCIe NVMe Gen3X2X2
	Maximum Sequential Read	Up to 2400 MB/s
	Maximum Sequential Write	Up to 1300 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature Features	32° to 158°F (0° to 70°C) [ambient temp]
	realures	ATA Security; TRIM; L1.2



SSD 512GB 2280 M2 PCIe-	Form Factor	M.2 2280	
3x4 SS NVMe TLC	Capacity	512 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen3X4	
	Maximum Sequential Read	3100 ~ 3500 MB/s	
	Maximum Sequential Write	2400 ~ 2956 MB/s	
	Logical Blocks	1,000,215,215	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security; TRIM; L1.2	
SSD 256GB 2280 M2 PCIe-	Form Factor	M.2 2280	
3x4 SS NVMe TLC	Capacity	256 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen3X4	
	Maximum Sequential Read	2800 ~ 3500 MB/s	
	Maximum Sequential Write	1400 ~ 2200 MB/s	
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security; TRIM; L1.2	
SSD 256GB 2280 PCIe-3x4	Form Factor	M.2 2280	
NVMe Self Encrypted OPAL2		256 GB	
Three Layer Cell	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen3X4	
	Maximum Sequential Read	2800 ~ 3500 MB/s	
	Maximum Sequential Write	1663 ~ 2200 MB/s	
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2	



Technical Specifications

SSD 512GB 2280 PCIe-3x4	Form Factor	M.2 2280
NVMe Self Encrypted OPAL2	Capacity	512 GB
Three Layer	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	3100 ~ 3500 MB/s
	Maximum Sequential Write	2400 ~ 2956 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

NETWORKING/COMMUNICATIONS

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) ^{*,**} Non-vPro		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11r IEEE 802.11r IEEE 802.11v
	Interoperability	Features Wi-Fi 6 technology
	Frequency Band	 802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only
	Not all configuration	components are available in all regions (countries

Not all configuration components are available in all regions/countries. c06725591 — DA16750 — Worldwide — Version 2— November 4, 2020

	 AES-CCMP: 128 bit in h 802.1x authentication WPA, WPA2: 802.1x. W WPA2 certification IEEE 802.11i WAPI 	ardware /PA-PSK, WPA2-PSK, TKIP, and AES.
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access P	oint Required)
Roaming	IEEE 802.11 compliant r	oaming between access points
Output Power ²	 802.11b: +18.5dBm mi 802.11g: +17.5dBm mi 802.11a: +18.5dBm mi 802.11a: +18.5dBm mi 802.11n HT20(2.4GHz) 802.11n HT40(2.4GHz) 802.11n HT40(5GHz): - 802.11ac VHT80(5GHz) 802.11ac VHT160(5GH 802.11ax HT40(2.4GHz) 802.11ax VHT160(5GHz) 	inimum inimum): +15.5dBm minimum): +14.5dBm minimum +15.5dBm minimum +14.5dBm minimum): +11.5dBm minimum z): +11.5dBm minimum z): +10dBm minimum
Power Consumption	 Transmit mode: 2.0 W Receive mode:1.6 W Idle mode (PSP) 180 m Idle mode: 50 mW (WL Connected Standby/Me Radio disabled: 8 mW 	AN unassociated)
Power Management	ACPI and PCI Express con power saving mode	npliant power management 802.11 compliant
Receiver Sensitivity ³	 802.11b, 1Mbps: -93.5 802.11b, 11Mbps: -844 802.11a/g, 6Mbps: -86 802.11a/g, 54Mbps: -7 802.11n, MCS07: -67df 802.11n, MCS15: -64df 802.11ac, MCS0: -84df 802.11ac, MCS9: -59df 802.11ax, MCS11(HT44 802.11ax, MCS11(VHT 	dBm maximum dBm maximum '2dBm maximum Bm maximum Bm maximum Bm maximum Bm maximum
Antenna type	enclosure Two embedded dual bar	with spatial diversity, mounted in the display nd 2.4/5 GHz antennas are provided to the card to nmunications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCar	d with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 2. Type 1216: 1.67 x 12.	
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)



Technical Specifications

Altitude		Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activ	•	LED Amber – Radio OFF LED Off – Radio ON	
HP Integrated Module with Bluetoo	th 4.0/4.1/4.2/5.0	Wireless Technology	
Bluetoot	h Specification 4	4.0/4.1/4.2/5.0/5.1 Comp	liant
Frequenc	z y Band 2	2402 to 2480 MHz	
Number (Channels		.egacy: 0~79 (1 MHz/CH) 3LE: 0~39 (2 MHz/CH)	
Signaling	E	egacy: 3 Mbps signaling of BLE: 1 Mbps signaling data BLE: 1 Mbps signaling data I. Actual throughput may	a rate ¹ 0.2 Mbps
	c L	hannels Legacy: Asynchronous Cor	nection Oriented links up to 3, 64 kbps, voice nnection Less links 2178.1 kbps/177.1 kbps 4 kbps symmetric (3-EV5)
Transmit			shall operate as a Class II Bluetooth device with er of + 9.5 dBm for BR and EDR.
Power Co	- F	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Bluetoot Supporte Link Top	d	Microsoft Windows Blueto	oth Software
Power Ma	anagement M	Microsoft Windows ACPI, a	and USB Bus Support
Certifica	tions F	FCC (47 CFR) Part 15C, Sec	tion 15.247 & 15.249
Power Ma Certifica	tions L	TS 300 328, ETS 300 826 .ow Voltage Directive IECS JL, CSA, and CE Mark	
Supporte	ed L L L L L L L L L L L L L L L L L L L	3T4.1-ESR 5/6/7 Complian E Link Layer Ping E Dual Mode E Link Layer E Low Duty Cycle Directer E Low Duty Cycle Directer E L2CAP Connection Orien Train Nudging & Interlaced T4.2 ESR08 Compliance E Secure Connection- Bas E Privacy 1.2 –Link Layer E Privacy 1.2 –Link Layer E Privacy 1.2 –Extended S E Data Packet Length Ext FAX Profile (FAX) Basic Imaging Profile (BIP) Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distributio	d Advertising nted Channels d Scan sic/Full Privacy Scanner Filter Policies tension

Wireless access point and Internet service is required. Availability of public wireless access point is limited.
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
 Check latest software/driver release for updates on supported security features.



Technical Specifications

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

*Wi-Fi supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160MHz channels.

** Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it

may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

Intel Jefferson Peak2 9560 802.11a/b/g/n/ac (2x2) WiFi® and Bluetooth® 5.0 Combo ¹ non-vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi [®] CERTIFIED modules
	Frequency Band	 802.11b/g/n 2.402 - 2.482 GHz 802.11a/n/ac 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, , 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum



Technical Specifications

Power Consumption	 802.11n HT20(2.4GHz) 802.11n HT40(2.4GHz) 802.11n HT20(5GHz): 802.11n HT40(5GHz): 802.11ac VHT80(5GHz) 802.11ac VHT160(5GH) Transmit mode: 2.0 W Receive mode:1.6 W Idle mode (PSP) 180 m Idle mode: 50 mW (WL) Connected Standby/Mo Radio disabled: 8 mW): +14.5dBm minimum +15.5dBm minimum +14.5dBm minimum): +11.5dBm minimum Iz): +11.5dBm minimum W (WLAN Associated) AN unassociated)	
Power Management	ACPI and PCI Express con 802.11 compliant power	mpliant power management r saving mode	
Receiver Sensitivity ⁴	 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 		
Antenna type	enclosure Two embedded dual bar	with spatial diversity, mounted in the display nd 2.4/5 GHz antennas are provided to the card to nmunications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCar	d with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF LED Off – Radio ON		

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)



Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ throughput up to2.17 Mbps BLE: 1 Mbps signaling data rate ¹ throughput up to 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



NXP NPC300 Near Field Communication Module	Dimensions (L x W x H) Chipset	Module 17 mm by 10 mm by 2.0 mm NPC300
	System interface	I2C
	NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
	Reader (PCD-VCD) Mode ¹	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards 1. With application or UICC support
	Card Emulation (PICC- VICC) Mode ¹	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa 1. With application or UICC support
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
	Operating temperature	-25°C to 80°C
	Storage temperature	-25°C to 125°C
	Humidity	10-90% operating 5-95% non-operating
	Supply Operating voltage	2.7 to 5.5 Volts
	I/O Voltage	1.8V or 3.3V
Power Consumption		
(Booster enable, VBAT= 3	8.3V, VCC_BOOST = 5V)	
	Mode	Power Consumption, Typical Actual Power Consumption is dependent on NFC antenna and ma

moue	Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured.
Polling	710.93 mW
Detected Test Tag Type 1 Detected Test Tag Type 2	
Detected Test Tag Type 3	383.76 mW
Detected Test Tag Type 4	312.26 mW
Antenna	Antenna connector, 0.3mm pitch, 7 connector FPC. Antenna matching is external to module.



POWER

AC Adapter 45 Watt nPFC	Dimensions (H x W x D)	94.0 x 40.0 x 26.5 mm	
Standard USB Type-C® Straight 1.8m	Weight	192.5g +/-10%	
Straight 1.0m	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V : 81.5% 9V : 86.7% 12V : 87.41% 15V : 87.8%
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	5V/15W 9V/27W 12V/36W 15V/45W
		DC output	5V/9V/12V/15V
		Hold-up time	5 ms at 115 Vac input
	Connector	USB Type-C®	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar SELV; Agency approvals – FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE. 5 at 25°C ambient condition.



AC Adapter 45 Watt Smart	t Dimensions	95 x 45 x 26.8 mm	
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight	200 g +/- 10 g	
4.5mm Right Right 1.0m	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Certifications		ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B,
			s at 25°C ambient condition.
AC Adapter 45 Watt Smart	Dimensions		
nPFC Standard Barrel	t Dimensions Weight	MTBF - over 200,000 hour	
		MTBF - over 200,000 hour 95 x 45 x 26.8 mm	
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g	s at 25°C ambient condition.
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC 45 W
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power DC output	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC 45 W 19.5 V
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power DC output Hold-up time	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC 45 W 19.5 V 5 ms at 115 Vac input
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input Output	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power DC output Hold-up time Output current limit	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC 45 W 19.5 V 5 ms at 115 Vac input
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input Output Connector	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power DC output Hold-up time Output current limit 4.5mm Barrel Type Operating temperature	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC 45 W 19.5 V 5 ms at 115 Vac input <8.0A
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input Output Connector	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power DC output Hold-up time Output current limit 4.5mm Barrel Type Operating temperature Non-operating (storage)	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC 45 W 19.5 V 5 ms at 115 Vac input <8.0A 32°F to 95°F (0°to 35°C)
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight Input Output Connector	MTBF - over 200,000 hour 95 x 45 x 26.8 mm 200 g +/- 10 g Input Efficiency Input frequency range Input AC current Output power DC output Hold-up time Output current limit 4.5mm Barrel Type Operating temperature Non-operating (storage) temperature	s at 25°C ambient condition. 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 VAC 45 W 19.5 V 5 ms at 115 Vac input <8.0A 32°F to 95°F (0°to 35°C) -4°F to 185°F (-20°to 85°C)



	EMI and Safety Certifications	Worldwide safety standar SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE. s at 25°C ambient condition.
AC Adapter 65 Watt nPFC	Dimensions	90.0 x 51 x 28.5mm	
Standard USB type C [®] Straight 1.8m	Weight	250 g +/- 10 g	
Straight 1.0m	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.6 A at 90 VAC and maximum load
	Output	Output power	65 W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	8.0A Max.
	Connector	USB Type C®	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar SELV; Agency approvals - FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B 5 B, CCC, NOM-1 NYCE. is at 25°C ambient condition.
AC Adapter 65 Watt Smart	Dimensions (H x W x D)	102 x 55 x 30mm	
nPFC EM Barrel 4.5mm New EM	Weight	250g +/-10%	
ICAA FI.I	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	



Technical Specifications

		Output current limit	<11.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standard SELV; Agency approvals - (FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.
AC Adapter 65 Watt Smart	Dimensions (H x W x D)	90 x 51 x 28.5mm	
nPFC Standard Barrel 4.5mm Right Angle 1.8m	Weight	230g +/-10%	
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class E FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

Battery RH 3 Cell WHr 45		6.2 x 68.7 x 249.6mm
Long Life -PL Fast Charge	Weight	190g
	Cells/Type	3cell Lithium-Ion Polymer cell/ 545974

Not all configuration components are available in all regions/countries. c06725591 — DA16750 — Worldwide — Version 2— November 4, 2020

Technical Specifications

Voltage	11.4 V
Amp-hour capacity	3.950Ah
Watt-hour capacity	45 Wh
Operating (Charging)	32° to 113° F (0° to 45° C)
Operating (Discharging)	14° to 122° F (-10° to 60° C)
Optional Travel Battery Available	No
Warranty	Based on system offering

Country of Origin

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Business Backpack (up to 17.3")	2SC67AA
	HP Business Slim Top Load (up to 14.1")	2SC65AA
	HP Prelude Pro Recycle Backpack (Montrose)	1X644AA
	HP Prelude Pro Recycle Top Load (Midtown)	1X645AA
	HP Recycled Top Load	5KN29AA
	HP Recycled Backpack	5KN28AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Wired Desktop 320MK Mouse & Keyboard	9SR36AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP USB Travel Mouse	G1K28AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C Travel Hub G2	7PJ38AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA
	65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP 65W USB-C LC Power Adapter	TBD
	HP Power Bank	N9F71AA
	HP USB-C Notebook Power Bank	3TB55AA



Options and Accessories (sold separately and availability may vary by country)

Storage	HP External USB Optical Drive	F2B56AA
Security	HP Sure Key Cable Lock HP Nano Keyed Cable Lock	6UW42AA 1AJ39AA



Summary of Changes

Date of change:	Version History:		Description of change:
4 November 2020	V1 to V2	Updated	Removed - Intel® Iris® Xe Graphics from processor name and added Iris footnote in graphics section

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